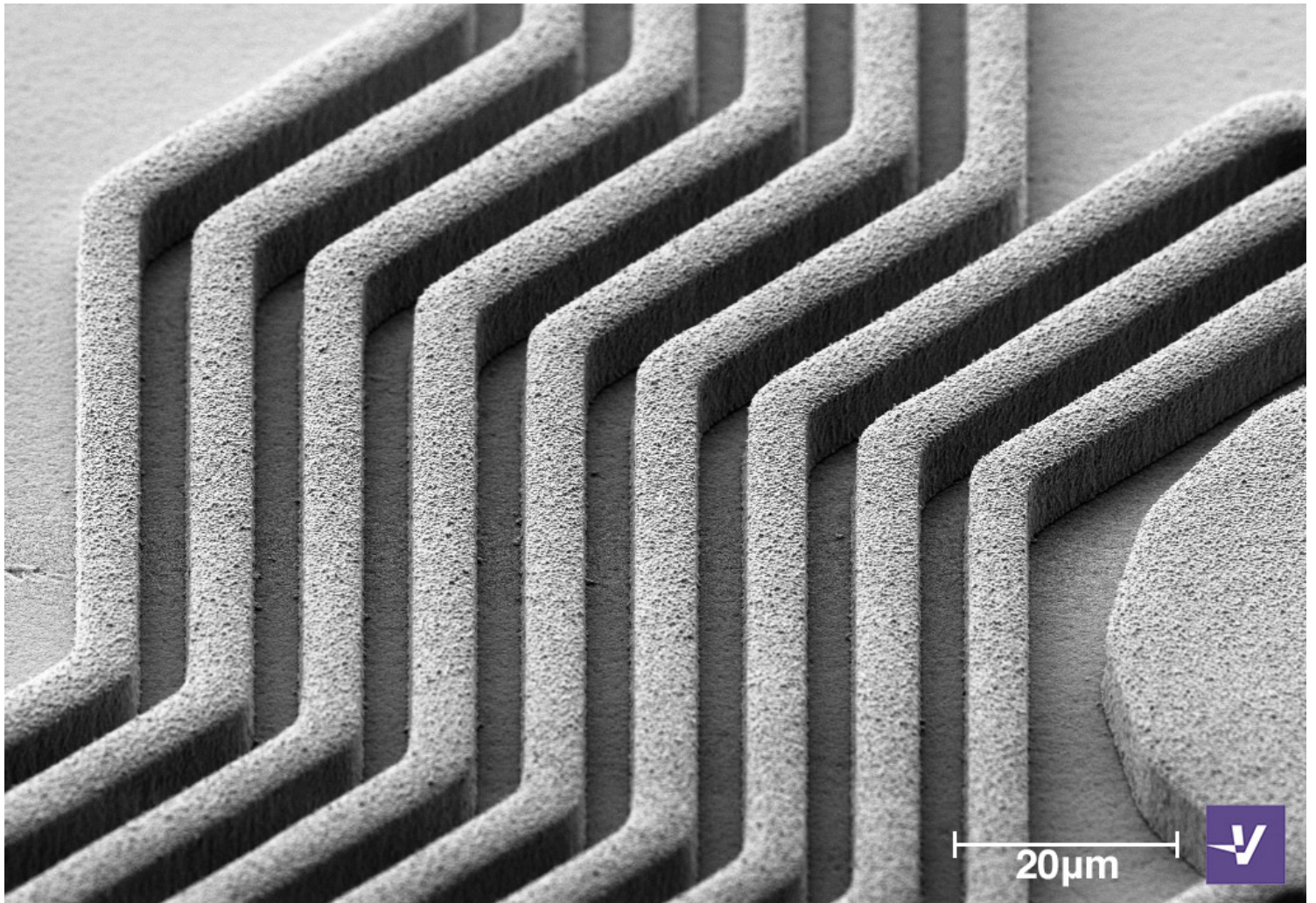


# MOVING ADVANCED PACKAGING FORWARD: VISITECH SPONSORS SYNAPS 2021

*Posted on April 28, 2021*

Visitech's strong focus on developing high-end subsystems for advanced packaging allows toolmakers to innovate better products more efficiently. Advanced packaging is essential to the semiconductor industry as the key driver and enabler for the electronics value chain.



With rapid development, learning what new product offerings are available and which direction

development is taking is key for tomorrow's industry to stay on top of innovation. A useful forum where leading companies can gain such insight is SYNAPS (***S**ymposium by **Y**ole Développement and **N**CAP on **A**dvanced **P**ackaging **S**emiconductors*). This is why Visitech will be a Gold Sponsor of the 2021 SYNAPS symposium, an online event on May 18-20, 2021.

– We look forward to the event and trust that participants will find Visitech's LUXBEAM® Lithography system, which enables better yield and precision, not only interesting but also instrumental when planning their next-generation direct imaging lithography solutions for advanced packaging, states Managing Director at Visitech, Øyvind Tafjord.

Find out more about the event [here](#).